



# CubeSat Technology Exploration Project - CubeSTEP

Additive Manufacturing in Creating a Universal Bus

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## Introduction to CubeSTEP



#### Project Project **Overview Objectives** Student led, multi-Design and manufacture a disciplinary collaborative project universal CubeSat testbed for between CPP and JPL TRL maturation Utilize additive manufacturing to integrate customized structures JPL University Crowdsourcing initiative (JUCI) and technology Design, develop and test an Started in Spring 2020 Oscillating Heat Pipe (OHP)

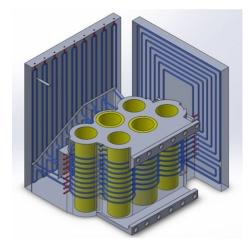
Sharlene Nazari

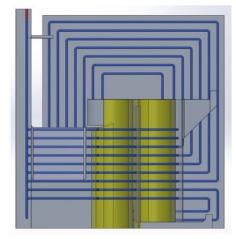


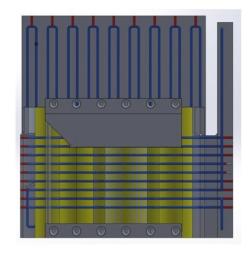
### Universal Testbed Purpose



- CubeSTEP's core objective is to create a universal testbed
- Standardized and Economic Platform
- Additive Manufacturing
  - $\circ$  Integration of complex geometries into bus structure









## **Universal Testbed**

High Level Requirements - 1



Level 2 Requirements		
Req. ID	Requirement	Rationale
M-1.0	The CubeSat Bus shall be capable of operating while in Low Earth Orbit	To increase TRL we need to be able to test payloads in Earth orbit
F-1.0	The CubeSat Bus shall be equipped with a dedicated flight software system	The CubeSat needs dedicated software to receive and send tasks to other parts of the mission
H-1.0	The CubeSat Bus shall utilize Commercial Off The Shelf (COTS) components for all subsystems	COTS will be used to decrease cost and lead time associated with creating in-house components
S-1.0	The CubeSat Bus shall provide a structure for avionics and the payload	The structure will be used to house all CubeSat components and provide Bus-Payload integration
C-1.0	The CubeSat shall be able to communicate with the Ground Station while in Low Earth Orbit	The CubeSat will need a subsystem to send data and receive commands from the Ground Station



## **Universal Testbed**

High Level Requirements - 2



Level 3 Requirements		
Req. ID	Requirement	Rationale
H-1.1	The CubeSat shall be able to compile, store, and manage payload data as well as commands from the Ground Station	The CubeSat needs to be able to process commands as well as collect data from testing and store that data until downlink
H-1.2	The CubeSat shall generate power using Solar Panels	Solar Panels are the cheapest and most available power generation option for CubeSats
H-1.3	The CubeSat shall have 3 axis stabilization	The CubeSat will need to know what its orientation is, how it is changing, and be able to control the orientation for power generation
H-1.4	The CubeSat shall be able to distribute its generated power to other components	Different components will have different voltage and power requirements, so the CubeSat needs to collect the power generated and distribute it accordingly
H-1.5	The CubeSat Bus shall be able to send data and receive commands from the Ground Station	The CubeSat will need to downlink data and receive commands from the ground



## Challenges in Creating a Common Bus

- Interfaces
  - $\circ$  Mechanical
    - Secure the payload to the bus
  - o Electrical
    - Feed wiring through the structure
  - $\circ$  Data
    - Varying component capabilities
    - Varying types of data collected and output
- Flight Software

   Modularity



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# Impact of Additive Manufacturing Design



- Design must be made with printer capabilities in mind
  - $\circ$  Print orientation
  - $\circ$  Support structures
  - o Size of structure
  - Complex geometries
    - Difficult and costly to machine
    - Can be 3D printed



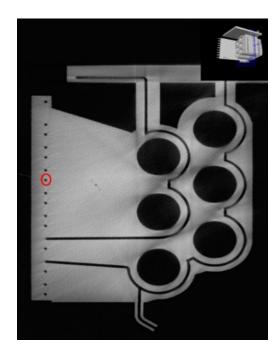


## **Impact of Additive Manufacturing**



Manufacturing

- Common materials are aluminum alloys
- Powder Bed Fusion
  - Fine layer of metal powder spread across preheated metal substrate
  - A layer of powder fully melted by laser energy across printing bed
  - Scanned according to predefined slice pattern
  - Process repeats
- Post Processing
  - $\circ$  Powder Removal
  - Surface Finishing
  - Heat Treatment





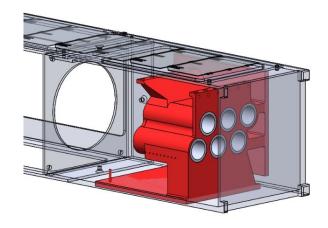
## **Impact of Additive Manufacturing**



 Additive manufacturing can allow for payloads to be integrated into the structure itself

Integration

- Payload and structure both 3d printed
- Allows for OHP walls to be exposed to space environment, acting as a heat sink

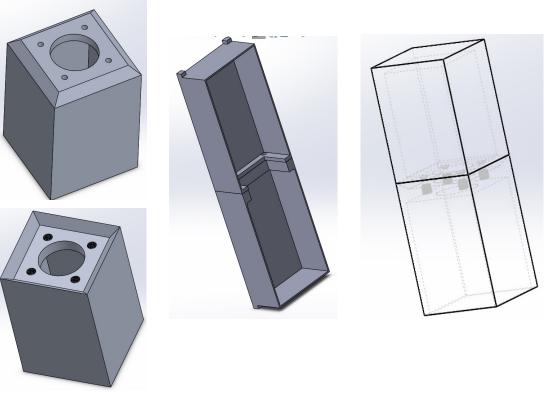




#### Bus Interfaces Mechanical

- Four key-locking inserts (ex. Keenserts) bonded into the bottom z-face of the OHP half of the bus. Suitable Allen-head fasteners used to attach other half of bus
- Key locking insert placement 3d printed into additively manufactured structure





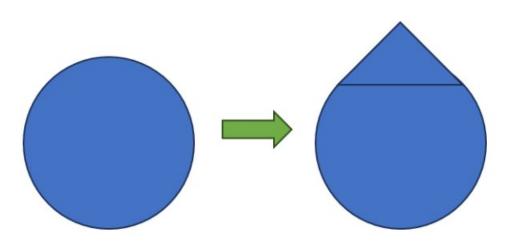


## 3D Design

Impact of AM in CubeSTEP

- Flat plate OHPs will be printed vertically
- Overhangs greater than 45° avoided
- Support structure inside thermal reservoir
- OHP channel diameter and turn radius determined by printer capabilities

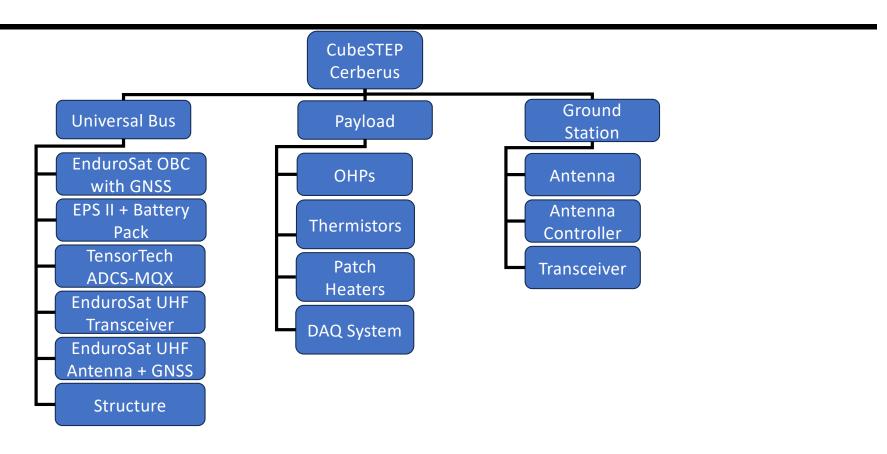






## System Level Design







Bus Capability Selected Boards

- EnduroSat
  - $_{\odot}$  Average Available Power: 10 W
  - Battery Capacity: 42 Wh (4S)
  - $_{\odot}$  Power Buses: 3V3, 5V, 12V, RAW (12-16.8V)
  - C&DH: Arm Cortex M7 with 2 MB Flash; Up to 480 MHz; 1x MicroSD card slot
  - Telemetry Data Rate: Up to 100 kbps
  - Payload Data Rate: Up to 125 Mbps

o Data Interfaces: 4x RS-422/485; 2x I<sup>2</sup>C; 2x UART; 8x GPIO; 1x CAN; Ethernet

TensorTech ADCS-MTQ

 Pointing Accuracy: 5 deg @ Sunlight
 Torque: < 0.01 mNm</li>
 Slew Rate: 1 deg/s

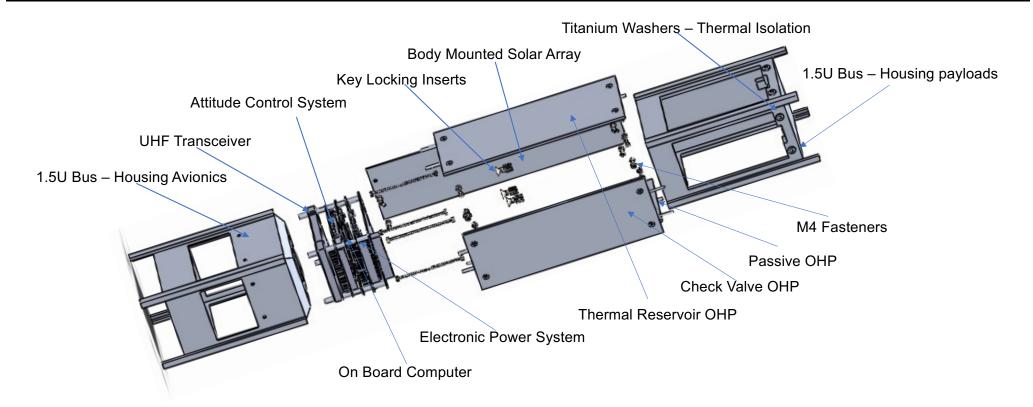


**ENDUROSAT** 





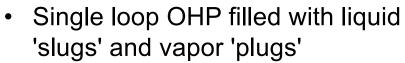




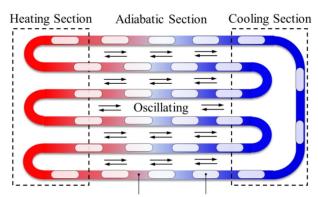


## **Payload Concept**

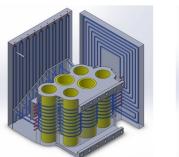
Oscillating Heat Pipe Integrated Battery Case

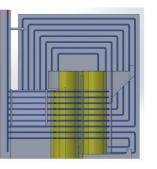


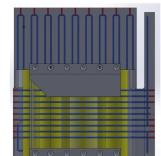
- Phase change facilitates higher heat transfer and mitigates thermal runaway
- Regulates battery temperature with high discharge rate
- Addresses critical thermal management challenges and enables higher-power missions



Liquid Slug Vapor Plug



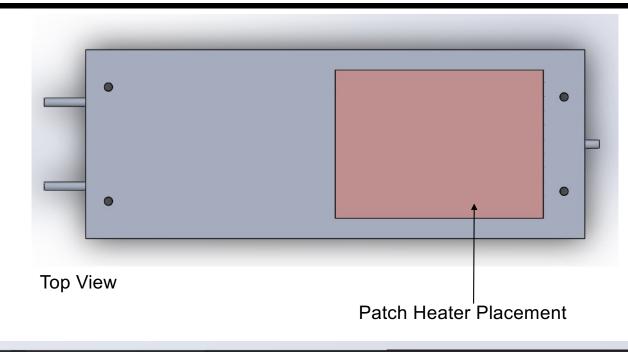




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Side View

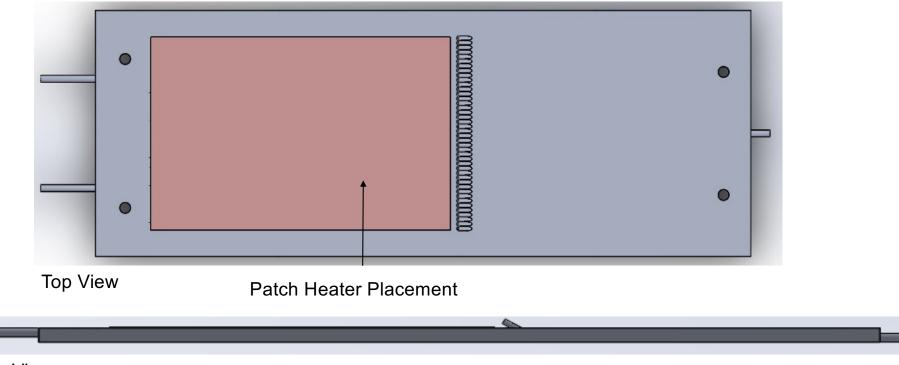
Andres Cuevas



## **CubeSTEP Cerberus**



Check Valve OHP

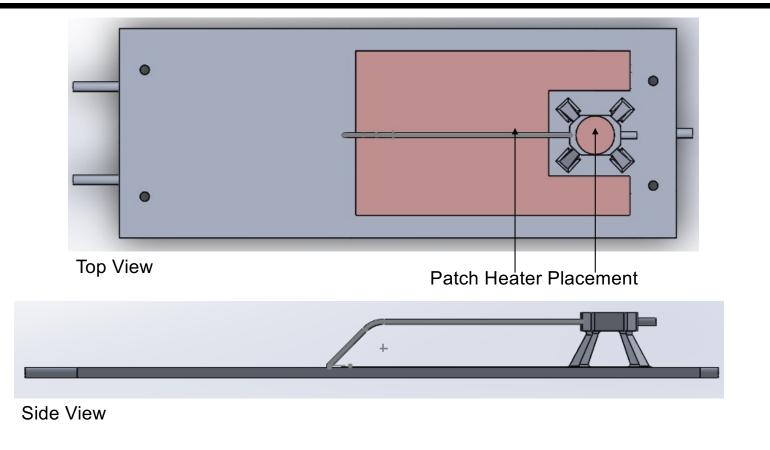


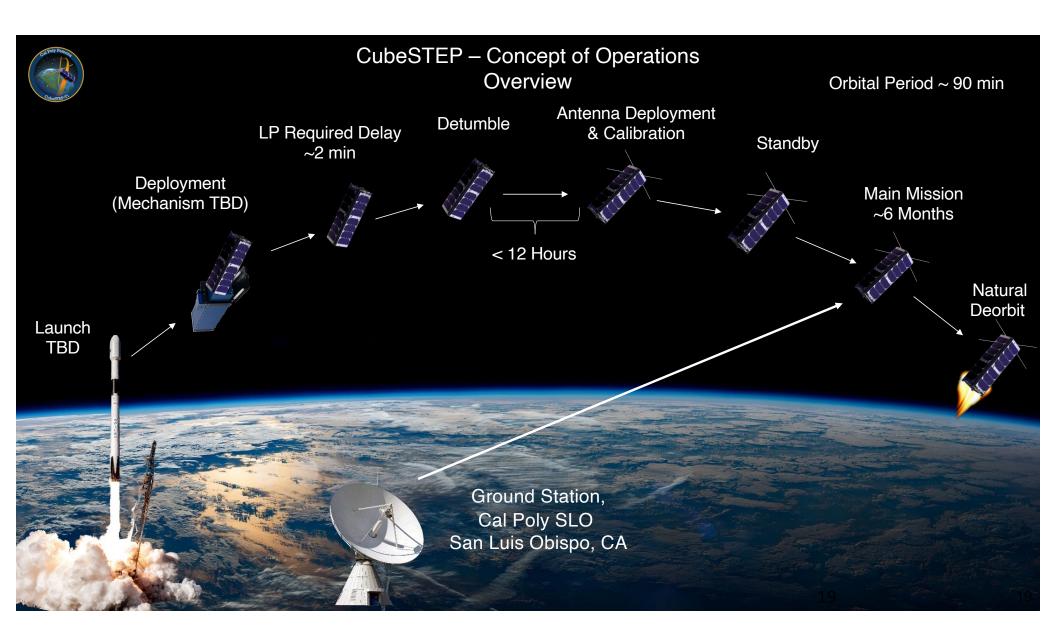


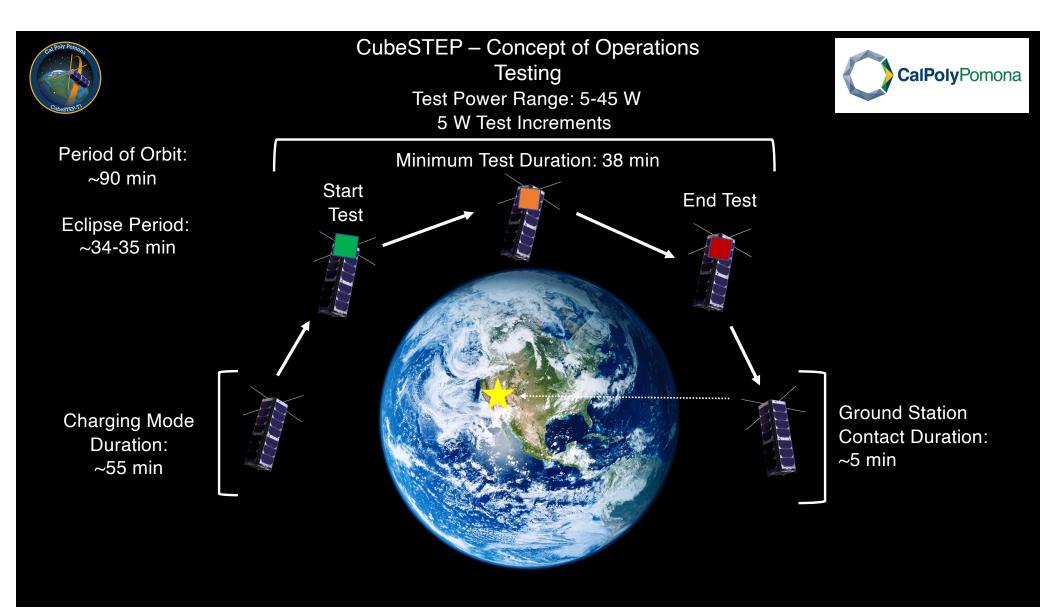
## **CubeSTEP Cerberus**



Thermal Reservoir OHP









## Conclusion



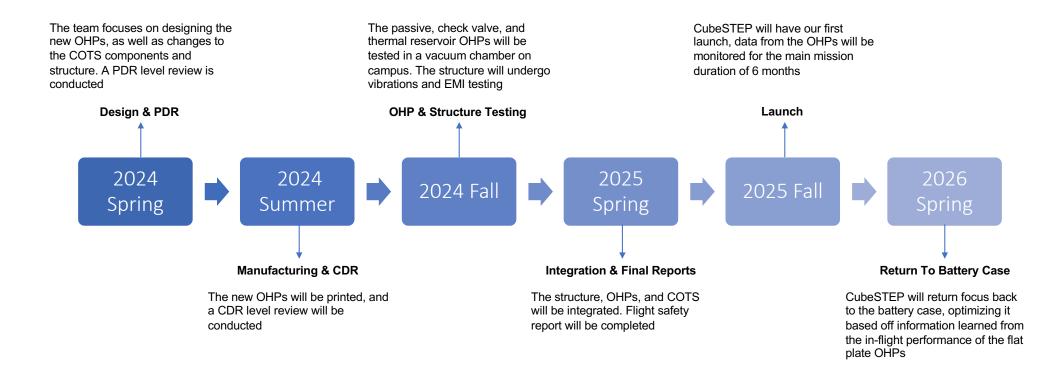
- Additive manufacturing is a critical tool in designing a universal testbed

   Enables the design of complex geometries
   Diverse technologies can be integrated directly into bus structure
- Challenges to be overcome:
  - o Mechanical, Electrical, & Data Interfaces
  - Modular Flight Software



#### **Next Steps**









# Thank you!



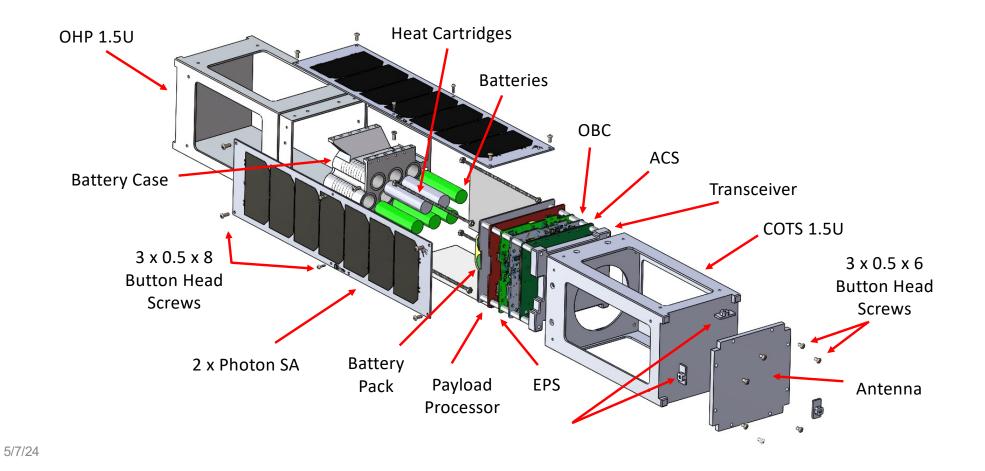


# Appendix



### **Structures** *Exploded View of 3U CubeSat*



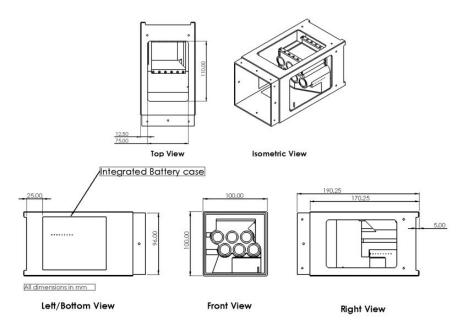


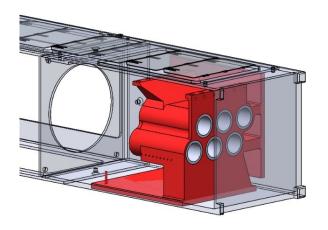
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## **AM - OHP Integration**

OHP Battery Case Embedded in Structure





OHP –Battery Case Embedded Into Structure

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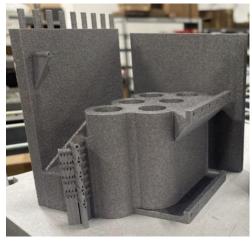
## **Design and Manufacturing**



#### Design

Payload

Optimal geometry utilizing minimal material ANSYS & nTopology



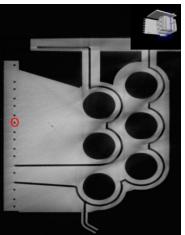
#### Fabrication

Powder Bed Fusion AlSi10Mg Achieve complex geometry



#### **Post Processing**

Post printing CT Scan Powder Detection Powder removal



#### **Post Processing**

Remove drain port & weld Charge valve & fill R134a Leak test

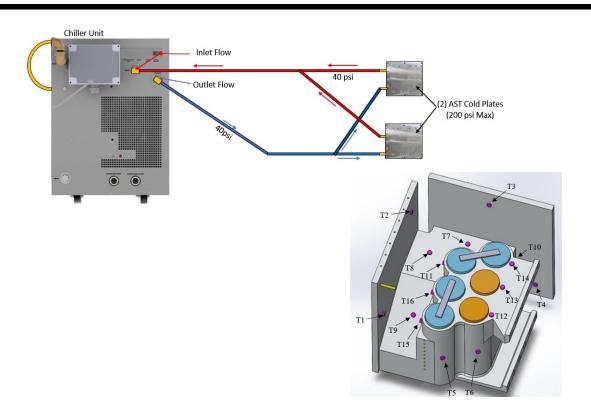




### **Ground Testing** *Chiller Testing*



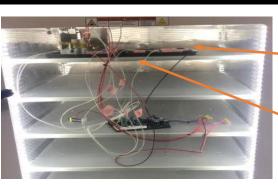
- Objective:
  - Characterize & test functionality of charged vs. uncharged battery case
- Method:
  - Tested OHP filled to 49.7% with R134a and empty
  - Used Chiller with cold plates to simulated space environment
  - $_{\odot}$  Tested at 45° orientation
  - $_{\odot}$  Tested at 25° C
  - Tested at 40 PSI





### **Ground Testing** Vacuum Testing

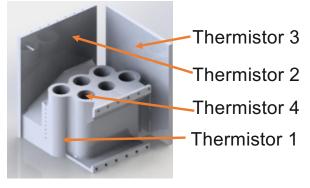
- Objective:
  - Determine proper OHP thermal load under radiative cooling environment
  - $\circ\,$  Characterize OHP under extreme heat loads
  - Characterize & optimize battery configuration
    - Used heat cartridges to simulate extreme battery temperatures
- Method:
  - OHP with thermal cartridges inside, hooked up to lithium-ion batteries, placed in vacuum chamber
  - o Vary duty cycle of thermal cartridges
  - Record temperature data at 6 points on OHP, batteries and thermal cartridges using thermistors



Thermistor 6 (on End of 4 Battery Chain)

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Thermistor 5 (On End of 4 Battery Chain)

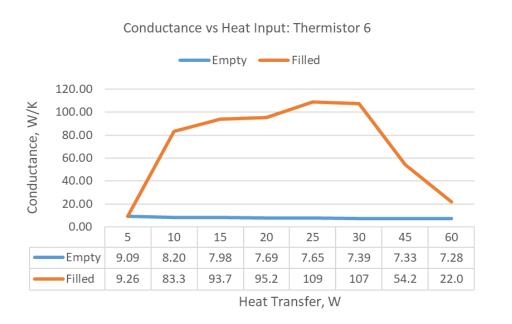




# Performance

Chiller Test Results

- Chiller Test Results
  - $\circ$  14.5x peak increase in conductivity
  - Matched expectations of JPL technologist
  - $\circ$  Demonstrated dry-out as expected



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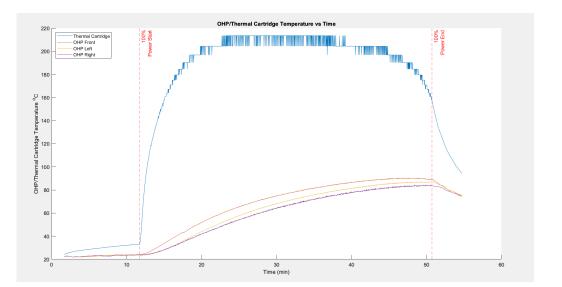
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## Performance

Vacuum Test Results

- Vacuum Testing
  - Battery output determined to be optimized in a series configuration
  - OHP effectively mitigates thermal runaway
    - Heat cartridges reached up to 213°C while battery case averaged ~87°C
    - Average battery temperature in series was ~60°C



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## System Level Design



